Ning-Cheng Lee Biography

Ning-Cheng Lee has 30 years plus of experience in fluxes, solder pastes, underfills and adhesives developments for SMT industries. He authored “Reflow Soldering Processes and Troubleshooting: SMT, BGA, CSP, and Flip Chip Technologies”, and co-author of “Electronics Manufacturing with Lead-Free, Halogen-Free, and Conductive-Adhesive Materials” and several lead-free soldering books. He received several major industry awards from SMT Magazine, SMI or SMTA International Conferences, IPC for Honorable Mention Paper and of SMTA China South Conference. He was honored as 2002 Member of Distinction from SMTA, 2003 Lead Free Co-Operation Award from Soldertec, 2006 Exceptional Technical Achievement Award from CPMT, 2007 Distinguished Lecturer from CPMT, 2009 Distinguished Author from SMTA, 2010 Electronics Manufacturing Technology Award from CPMT, 2015 IEEE Senior Member, 2015 Founder’s Award from SMTA, and 2017 IEEE Fellow. He has served on the board of governors for CPMT and SMTA board of directors. He serves also as editorial advisory board of Soldering and Surface Mount Technology, Global SMT & Packaging and as associate editor for IEEE Transactions on Components Packaging Manufacturing Technology. He has numerous publications and frequently served as a keynote speaker worldwide.